

Novel Epoxy Hardeners for Improved Properties, Processing and Handling

Abstract of the Disclosure

Hardeners for epoxy resins are disclosed which have the capability of curing at lower temperatures than currently available hardeners while retaining superior mechanical and thermal properties. An especially useful hardener combines imidazole, tetramethylguanidine or tetramethylguanidine adduct, and trimethylolpropane to produce a hardener having a latency period of up to about 24 hours and which cures at temperatures as low as about 60°C. A second hardener mixture is composed of 2, 6-bis(hydroxymethyl)-p-cresol, tetramethylguanidine and trimethylolpropane. Accelerators and other materials are added as needed to modify the cure time and temperature to suit particular applications. A method for making the hardener is also disclosed.

First	2nd	3rd	4th	5th	6th	7th	8th	9th	10th	11th	12th	13th	14th	15th	16th	17th	18th	19th	20th	21st	22nd	23rd	24th	25th	26th	27th	28th	29th	30th	31st	32nd	33rd	34th	35th	36th	37th	38th	39th	40th	41st	42nd	43rd	44th	45th	46th	47th	48th	49th	50th	51st	52nd	53rd	54th	55th	56th	57th	58th	59th	60th	61st	62nd	63rd	64th	65th	66th	67th	68th	69th	70th	71st	72nd	73rd	74th	75th	76th	77th	78th	79th	80th	81st	82nd	83rd	84th	85th	86th	87th	88th	89th	90th	91st	92nd	93rd	94th	95th	96th	97th	98th	99th	100th
First	2nd	3rd	4th	5th	6th	7th	8th	9th	10th	11th	12th	13th	14th	15th	16th	17th	18th	19th	20th	21st	22nd	23rd	24th	25th	26th	27th	28th	29th	30th	31st	32nd	33rd	34th	35th	36th	37th	38th	39th	40th	41st	42nd	43rd	44th	45th	46th	47th	48th	49th	50th	51st	52nd	53rd	54th	55th	56th	57th	58th	59th	60th	61st	62nd	63rd	64th	65th	66th	67th	68th	69th	70th	71st	72nd	73rd	74th	75th	76th	77th	78th	79th	80th	81st	82nd	83rd	84th	85th	86th	87th	88th	89th	90th	91st	92nd	93rd	94th	95th	96th	97th	98th	99th	100th